T-1 3/4 (5mm) SOLID STATE LAMP

Part Number: WP7113SET Super Bri

Super Bright Orange

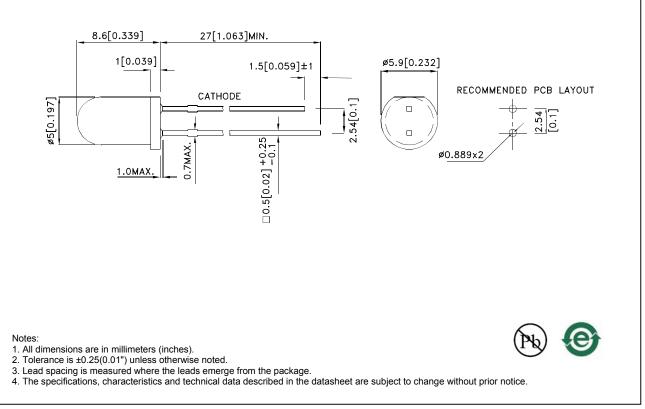
Features

- Low power consumption.
- Popular T-1 3/4 diameter package.
- General purpose leads.
- Reliable and rugged.
- Long life solid state reliability.
- Available on tape and reel.
- RoHS compliant.

Description

The Super Bright Orange device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

Package Dimensions



REV NO: V.6A CHECKED: Allen Liu DATE: JAN/20/2015 DRAWN: P.Cheng PAGE: 1 OF 6 ERP: 1101005215

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Selection Guide					
Part No.	Dice	Dice Lens Type Iv (mcd) [2] @ 20mA		/ - -	Viewing Angle [1]
			Min.	Тур.	201/2
WP7113SET	Super Bright Orange (AlGaInP)	Orango Transporont	2700	4200	20°
WF/1133E1		Orange Transparent	*1400	*2200	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.
*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	610		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Super Bright Orange	601		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	29		nm	IF=20mA
С	Capacitance	Super Bright Orange	30		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Orange	2	2.5	V	IF=20mA
lr	Reverse Current	Super Bright Orange		10	uA	VR = 5V

Notes: 1. Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V. 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

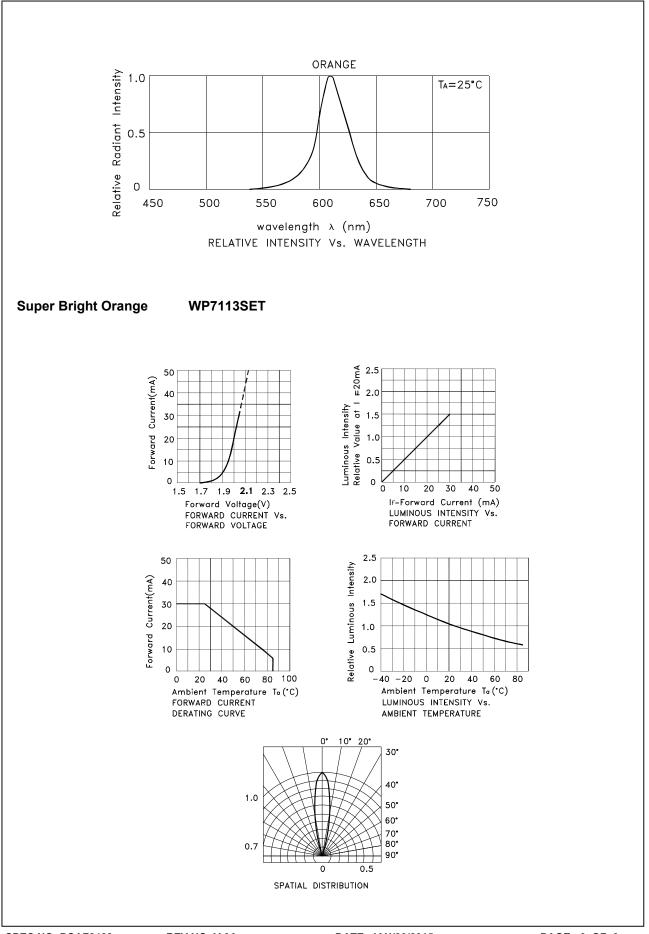
4. Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

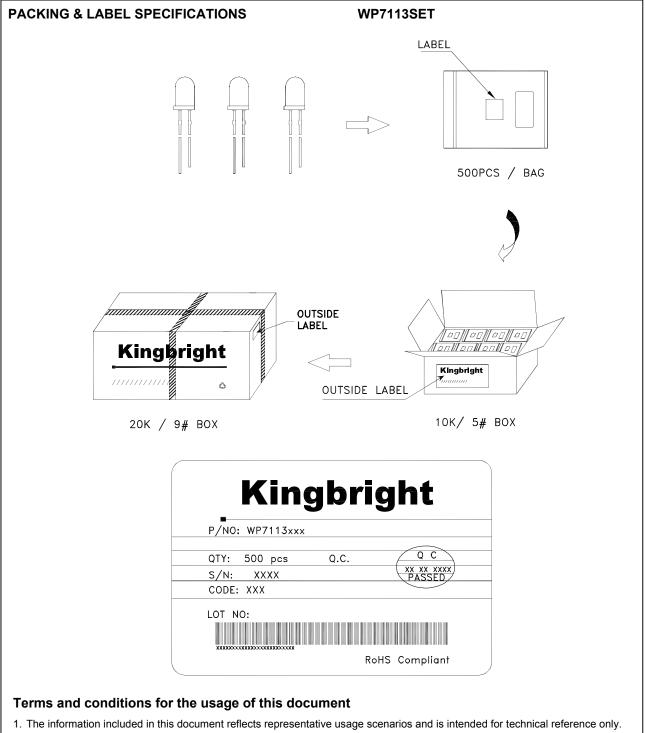
Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Orange	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	195	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.



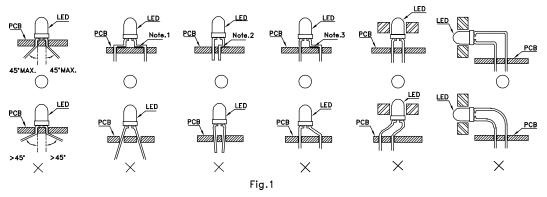


- 2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- 3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
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PRECAUTIONS

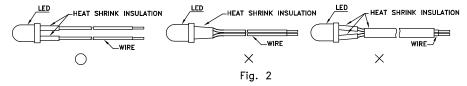
- 1. Storage conditions:
 - a.Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
 - b.LEDs should be stored with temperature \leq 30°C and relative humidity < 60%.
 - c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.
- 2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



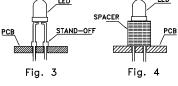
" \bigcirc " Correct mounting method "imes" Incorrect mounting method

Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

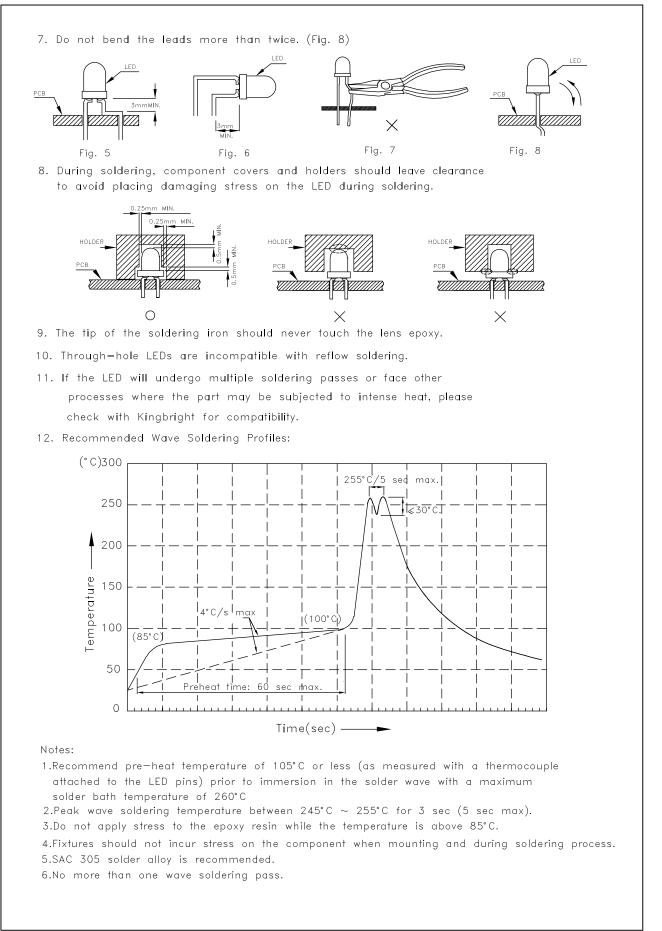
3. When soldering wires to the LED, each wire joint should be separately insulated with heat-shrink tube to prevent short-circuit contact. Do not bundle both wires in one heat shrink tube to avoid pinching the LED leads. Pinching stress on the LED leads may damage the internal structures and cause failure. (Fig. 2)



4. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 5. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 6. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)



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